

ATA6663/64 Errata and Data Sheet Clarifications

The functionality of the automotive qualified ATA6663/64 devices you have received is described in the Device Data Sheet 9146I-AUTO-10/14 except for the anomalies described in this document.

There are no silicon errata issues for the ATA6663/64. This document contains just some detailed information in addition to the ATA6663/64 Data Sheet 9146I-AUTO-10/14.

There is no change in the product itself.

1.0 SILICON ISSUES

None.

2.0 DATA SHEET CLARIFICATIONS

In the device data sheet 9146I-AUTO-10/14, the following clarifications and supplements should be noted:

2.1 Package Drawing

The package drawings have been updated. They have been converted from the former Atmel style to the Microchip Format.

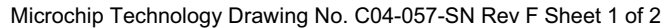
For the 8-lead SOIC package, the dimensions are identical, there are no changes in any dimensions.

For the ATA6663 in the 8-lead VDFN package, the only dimensions which are different are listed in the following table:

**TABLE 2-1: LIST OF UPDATED DIMENSIONS
(ONLY FOR THE ATA6663 IN THE 8-LEAD VDFN PACKAGE)**

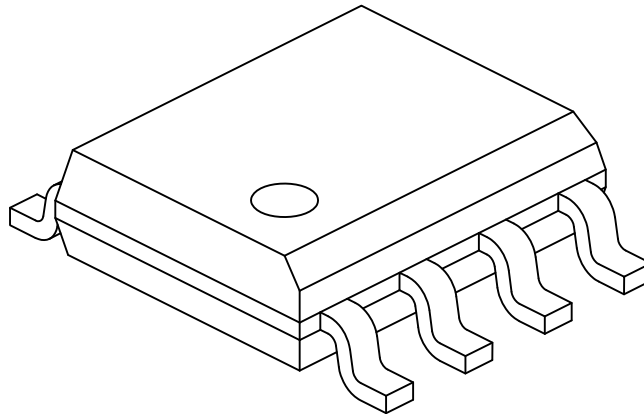
		OLD			NEW			
Dimension	Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.	Units
Overall Height	A	0.80	0.85	0.90	0.80	0.90	1.00	mm
Wettable Flank Step Length	D3	—	—	0.040	—	—	0.085	mm
Wettable Flank Step Heights	A4	0.10	—	0.15	0.10	—	0.19	mm

The new package drawings are depicted on the following 6 pages:



8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	4.90 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

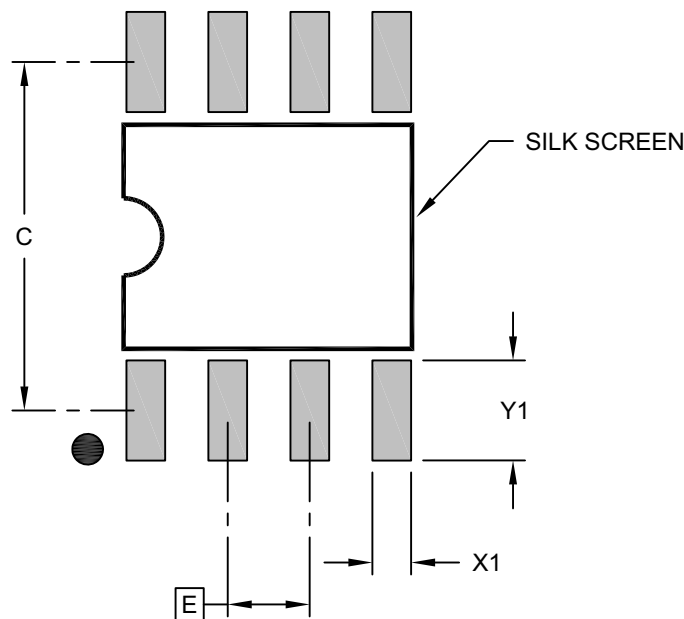
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-057-SN Rev F Sheet 2 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

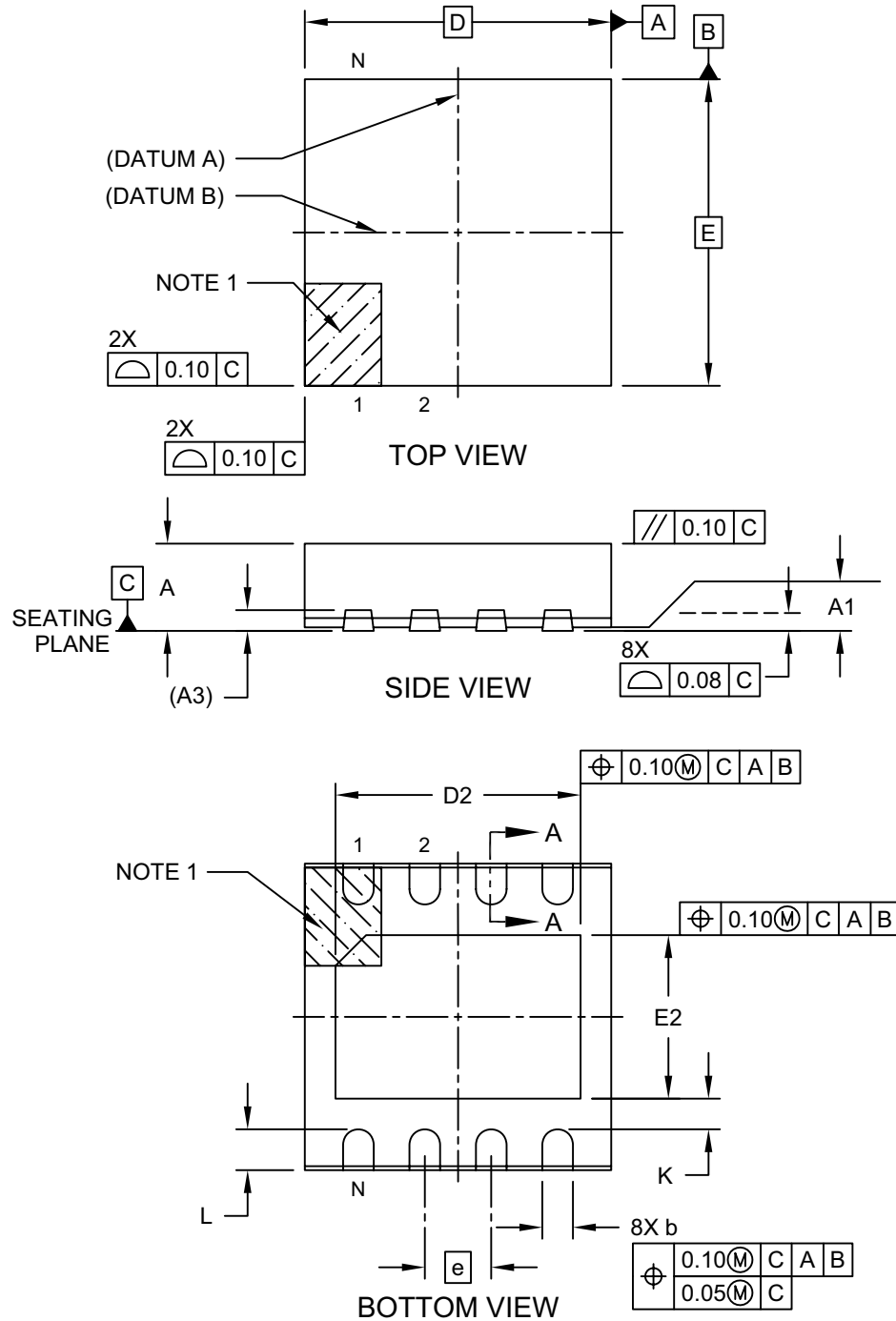
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2057-SN Rev F

8-Lead Very Thin Plastic Dual Flat, No Lead Package (Q8B) - 3x3 mm Body [VDFN] With 2.40x1.60 mm Exposed Pad and Stepped Wettable Flanks; Atmel Legacy YCL

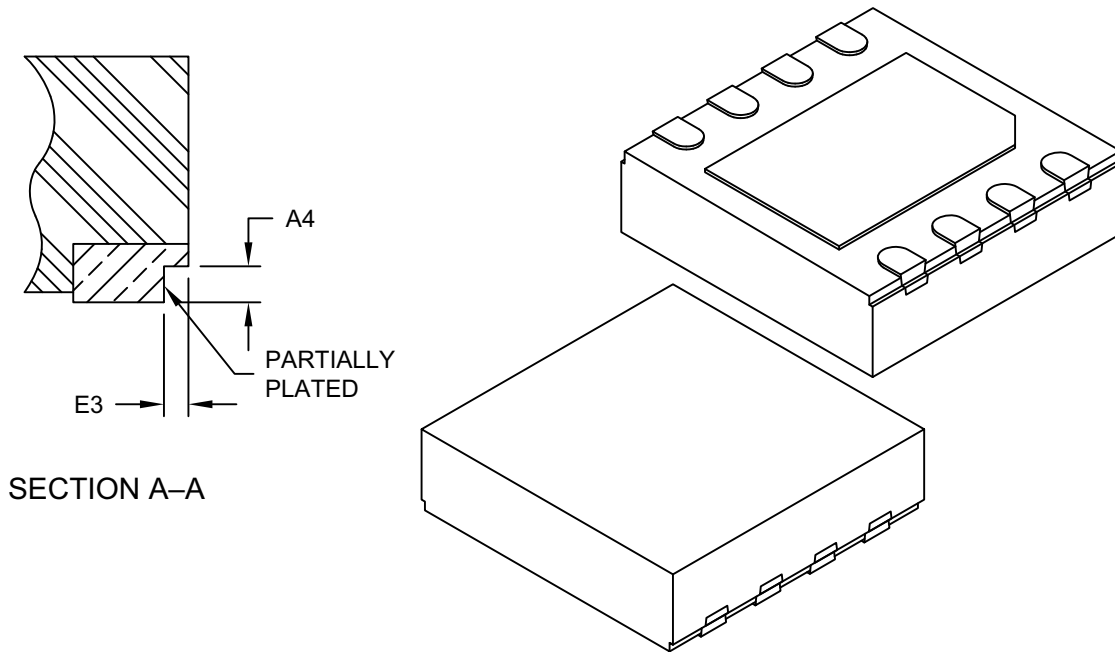
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-21358 Rev C Sheet 1 of 2

8-Lead Very Thin Plastic Dual Flat, No Lead Package (Q8B) - 3x3 mm Body [VDFN] With 2.40x1.60 mm Exposed Pad and Stepped Wettable Flanks; Atmel Legacy YCL

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.035	0.05
Terminal Thickness	A3	0.203 REF		
Overall Length	D	3.00 BSC		
Exposed Pad Length	D2	2.30	2.40	2.50
Overall Width	E	3.00 BSC		
Exposed Pad Width	E2	1.50	1.60	1.70
Terminal Width	b	0.25	0.30	0.35
Terminal Length	L	0.35	0.40	0.45
Terminal-to-Exposed-Pad	K	0.20	-	-
Wettable Flank Step Cut Depth	A4	0.10	-	0.19
Wettable Flank Step Cut Width	E3	-	-	0.085

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M

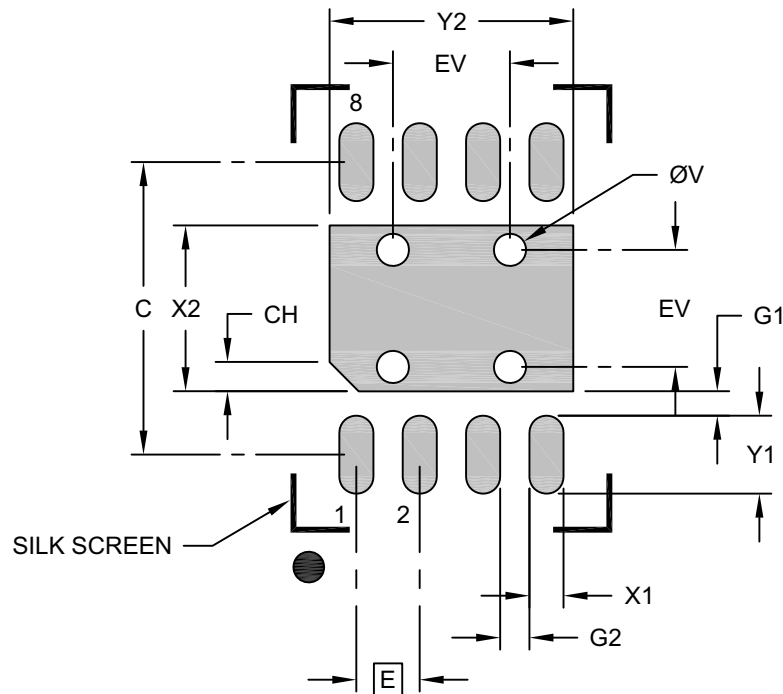
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21358 Rev C Sheet 2 of 2

8-Lead Very Thin Plastic Dual Flat, No Lead Package (Q8B) - 3x3 mm Body [VDFN] With 2.40x1.60 mm Exposed Pad and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			1.70
Optional Center Pad Length	Y2			2.50
Contact Pad Spacing	C		3.00	
Contact Pad Width (X8)	X1			0.35
Contact Pad Length (X8)	Y1			0.80
Contact Pad to Center Pad (X8)	G1	0.20		
Contact Pad to Contact Pad (X6)	G2	0.20		
Pin 1 Index Chamfer	CH	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

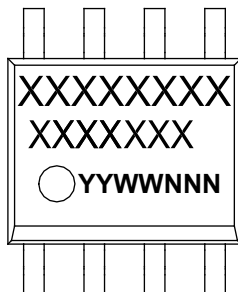
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-23358 Rev C

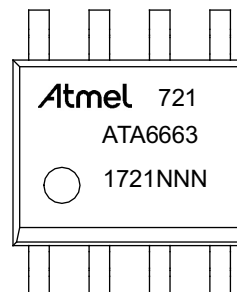
2.2 Package Marking Information

In the ATA6663/64 Data Sheet 9146I-AUTO-10/14, there is no information regarding the Package Marking. Therefore, the information is listed here:

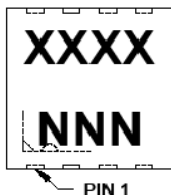
8-Lead SOIC



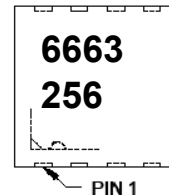
Example



8-Lead 3 X 3 mm VDFN



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC [®] designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

2.3 Trademarks Page

The information on [page 11](#) is also not available in the existing data sheet:

APPENDIX A: DOCUMENT REVISION HISTORY

Rev. A (March 2021)

- Initial Release of this Document: Errata released as a separate document. This Errata completes the Device Data Sheet 9146I-AUTO-10/14 with the following information:
 - Updated Package Drawing for the 8-Lead SOIC and the 8-Lead VDFN packages
 - Adding Package Marking Information
 - Updated Microchip Trademarks page

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- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
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- Microchip is willing to work with any customer who is concerned about the integrity of its code.
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